



Material Content Data Sheet



Sales Product Name		BTT6200-4EMA		Issued		1. August 2018		
MA#		MA001710520						
Package		PG-SSOP-24-14		Weight*		151.82 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.840	1.87	1.87	18706	18706
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		112	
	non noble metal	zinc	7440-66-6	0.068	0.04		446	
	non noble metal	iron	7439-89-6	1.355	0.89		8922	
wire	non noble metal	copper	7440-50-8	54.998	36.23	37.17	362268	371748
	non noble metal	copper	7440-50-8	0.627	0.41	0.41	4132	4132
	encapsulation	organic material	carbon black	1333-86-4	0.173	0.11		1142
encapsulation	plastics	epoxy resin	-	7.976	5.25		52537	
	inorganic material	silicondioxide	60676-86-0	78.546	51.75	57.11	517371	571050
leadfinish	non noble metal	tin	7440-31-5	2.911	1.92	1.92	19174	19174
plating	noble metal	silver	7440-22-4	1.379	0.91	0.91	9085	9085
glue	plastics	epoxy resin	-	0.162	0.11		1068	
	noble metal	silver	7440-22-4	0.765	0.50	0.61	5037	6105
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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